
Replacing TIOL111x with CCE4503

Abstract

This document contains all changes that might be necessary to replace the TIOL111x with the CCE4503.

Contents

Abstract	1
Introduction	2
Package size	2
Footprint change	3
Revision History	4
References.....	5
Status Definitions	5

Introduction

Package size

The package size of the CCE4503 and the TIOL111x is slightly different (see Figure 1).

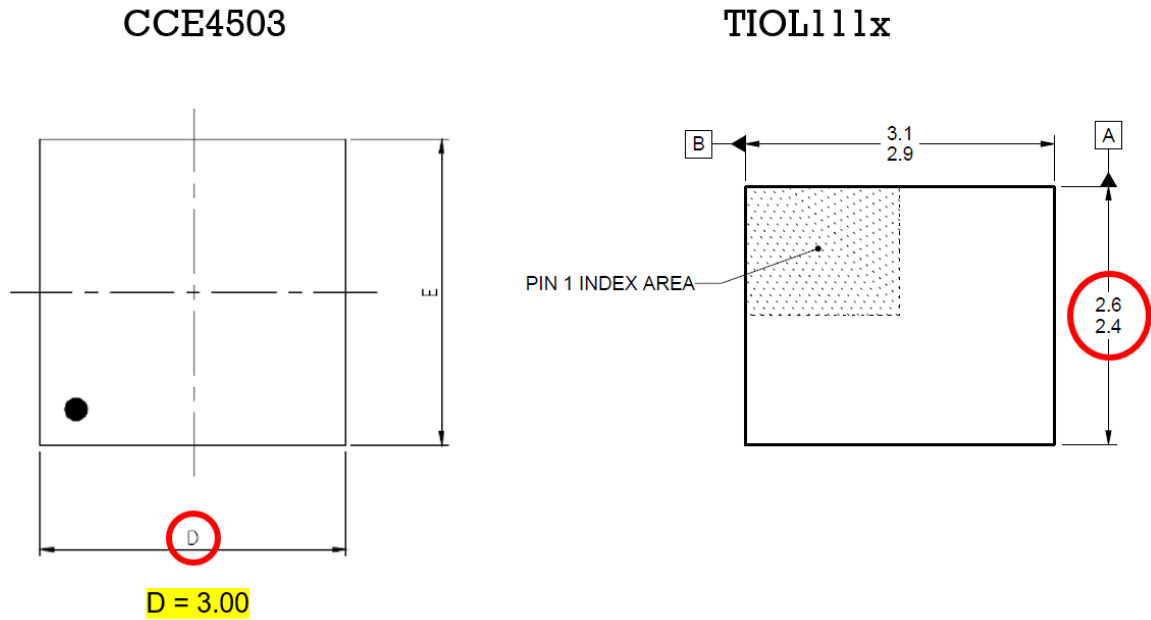


Figure 1: Package size comparison (in mm)

The CCE4503 has a package size of 3 mm x 3 mm while the TIOL111x (see References [2]) has a package size of 3 mm x 2.5 mm. This difference needs to be considered regarding the PCB layout. This does not affect the pitch between the pins.

Footprint change

Since the footprint of the TIOL111x and the CCE4503 have slightly differences it might be necessary to adapt the footprint on the PCB.

The difference is shown in the following figure.

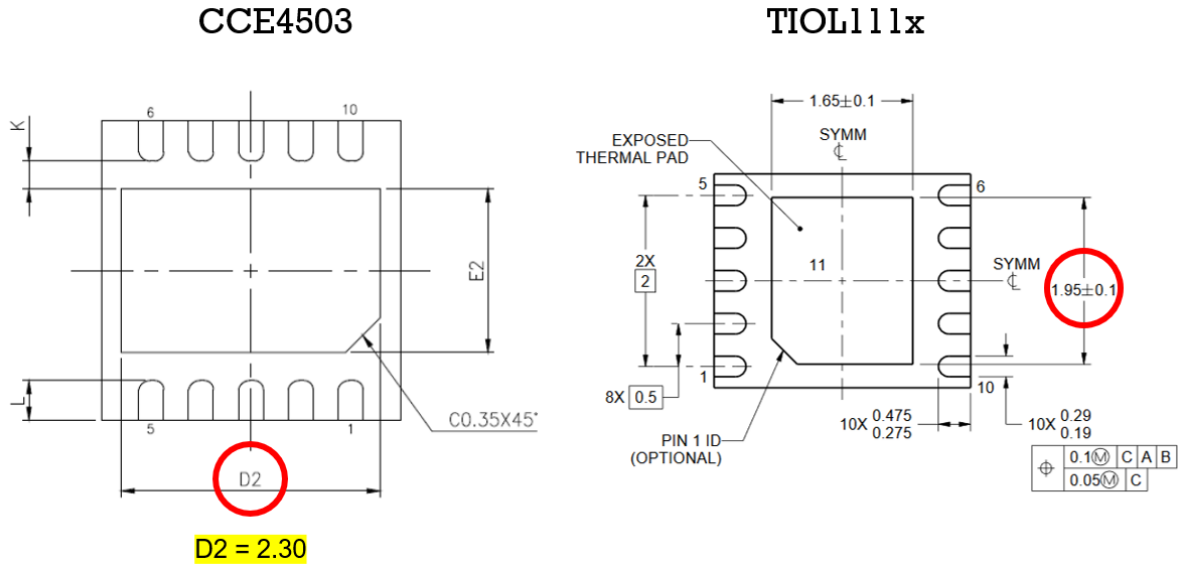


Figure 2: Footprint comparison (in mm)

The CCE4503 has an exposed pad length of 2.30 mm while the TIOL111x (see References [2]) has an exposed pad length of 1.95 mm. This difference needs to be considered regarding the PCB layout.

Revision History

Revision	Date	Description
3	28-Jan-2022	Rebrand
2	10-Dec-2020	Added package size comparison
1	01-Dec-2020	Initial version.

References

- [1] CCE4503, Datasheet, Dialog Semiconductor.
- [2] TIOL111x, Datasheet, Texas Instruments.

Status Definitions

Status	Definition
DRAFT	The content of this document is under review and subject to formal approval, which may result in modifications or additions.
APPROVED or unmarked	The content of this document has been approved for publication.

IMPORTANT NOTICE AND DISCLAIMER

RENESAS ELECTRONICS CORPORATION AND ITS SUBSIDIARIES (“RENESAS”) PROVIDES TECHNICAL SPECIFICATIONS AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES “AS IS” AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS OR IMPLIED, INCLUDING, WITHOUT LIMITATION, ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE, OR NON-INFRINGEMENT OF THIRD-PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for developers who are designing with Renesas products. You are solely responsible for (1) selecting the appropriate products for your application, (2) designing, validating, and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. Renesas grants you permission to use these resources only to develop an application that uses Renesas products. Other reproduction or use of these resources is strictly prohibited. No license is granted to any other Renesas intellectual property or to any third-party intellectual property. Renesas disclaims responsibility for, and you will fully indemnify Renesas and its representatives against, any claims, damages, costs, losses, or liabilities arising from your use of these resources. Renesas' products are provided only subject to Renesas' Terms and Conditions of Sale or other applicable terms agreed to in writing. No use of any Renesas resources expands or otherwise alters any applicable warranties or warranty disclaimers for these products.

(Disclaimer Rev.1.01)

Corporate Headquarters

TOYOSU FORESIA, 3-2-24 Toyosu,
Koto-ku, Tokyo 135-0061, Japan
www.renesas.com

Trademarks

Renesas and the Renesas logo are trademarks of Renesas Electronics Corporation. All trademarks and registered trademarks are the property of their respective owners.

Contact Information

For further information on a product, technology, the most up-to-date version of a document, or your nearest sales office, please visit www.renesas.com/contact-us/.